

Dual-Channel (N + M ≤ 8 phase) Step-Down, D-CAP+™ Digital Multiphase Controller with VR13.HC SVID and PMBus™ Interfaces

1 Features

- Input voltage range: 4.5V to 18V
- Output voltage range: 0.25V to 5.5V
- Intel® VR13.HC SVID compliant
- Dual output supporting M+N phase configurations: (N+M ≤ 8, M ≤ 4)
- Enhanced D-CAP+™ control to provide super transient performance with excellent dynamic current sharing
- Programmable loop compensations
- Programmable phase-firing order
- Individual phase current calibrations and reports
- Dynamic phase shedding with programmable current threshold for optimizing efficiency at light and heavy loads
- Fast phase-adding for undershoot reduction (USR)
- Driverless configuration for efficient high-frequency switching
- Fully compatible with TI NextFET™ power stage for high-density solutions
- Accurate, adjustable voltage positioning (AVP)
- Patented AutoBalance™ phase balancing
- Cycle-by-cycle per-phase current limit
- PMBus™ system interface for telemetry of voltage, current, power, temperature, and fault conditions
- New soft-shutdown option for over voltage fault
- 5mm × 5mm, 40-pin, QFN package

2 Applications

- [Data center & enterprise computing rack server](#)
- [Hardware accelerator](#)
- [Network interface card \(NIC\)](#)
- [ASIC and high performance client](#)

3 Description

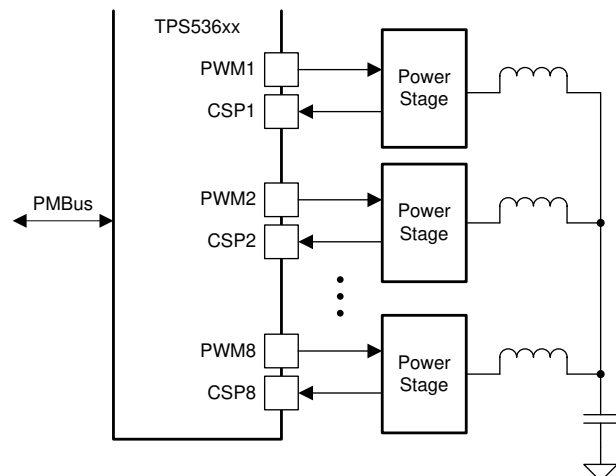
The TPS53688A is a fully VR13.HC SVID compliant step-down controller with dual channels, built-in non-volatile memory (NVM), and PMBus interface, and is fully compatible with TI NexFET smart power stage. Advanced control features such as DCAP+ architecture with undershoot reduction (USR) provide fast transient response, low output capacitance, and good current sharing. The device also provides novel phase interleaving strategy and dynamic phase shedding for efficiency improvement at different loads. Adjustable control of V_{CORE} slew rate and voltage positioning round out the VR13.HC SVID features. In addition, the device supports the PMBus communication interface for reporting the telemetry of voltage, current, power, temperature, and fault conditions to the systems. All programmable parameters can be configured by the PMBus interface and can be stored in NVM as the new default values to minimize the external component count.

The TPS53688A device is offered in a thermally enhanced 40-pin QFN package and is rated to operate from -40°C to 125°C.

Package Information

PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE (NOM)
TPS53688A	QFN (40)	5mm × 5mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



Simplified Application

4 Device and Documentation Support

4.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

4.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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4.3 Trademarks

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4.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

4.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

5 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
August 2025	*	Initial Release

6 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS53688ARSBR	Active	Production	WQFN (RSB) 40	3000 LARGE T&R	Yes	Call TI Nipdauag	Level-2-260C-1 YEAR	-	TPS 53688A

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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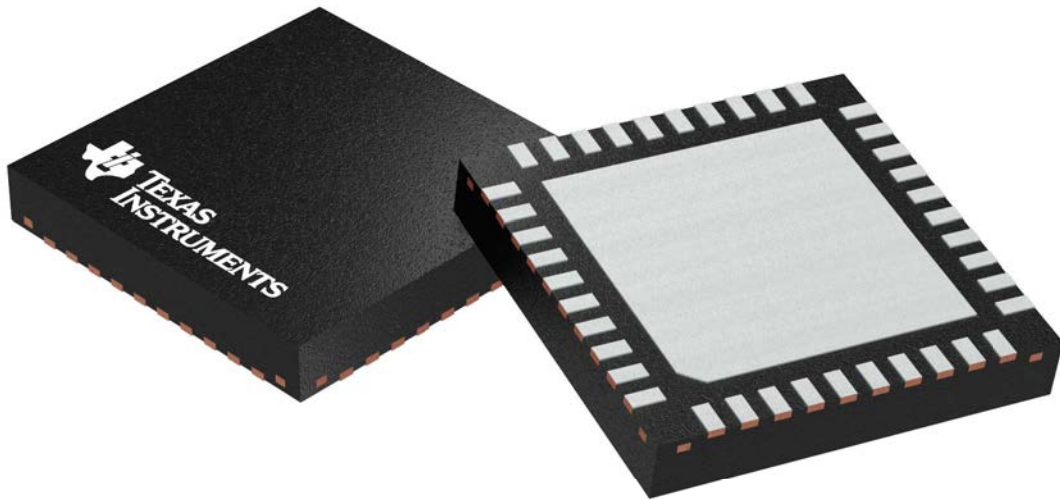
GENERIC PACKAGE VIEW

RSB 40

WQFN - 0.8 mm max height

5 x 5 mm, 0.4 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

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